

REMARKS

Claims 1-22 were pending when last examined, all of which stand rejected. During the telephone interview of May 24, 2004 with Examiner Chambliss, it was stipulated that use of the lapping process would distinguish Claim 1 from the cited references.

Claim 1 is amended to clarify what the lapping process entails. Since the abrasive lapping wheel is mentioned in the first paragraph on page 12 of the specification, no new matter is added. Claims 7-22 are amended for clarification and consistency with Claim 1.

The invention embodied in Claims 1-22 pertains to reconstruction of an IC package by electrically connecting a die to the lead frame of a pre-existing package and encapsulating the die. In the reconstruction process, lapping is used to shape the encapsulant of the new package.

While lapping is well known, it has heretofore not been applied for the purpose of encapsulant shaping, and especially for shaping an encapsulant in a reconstruction process. This invention is partially based on the discovery that lapping is well suited for encapsulant shaping in a chip reconstruction process because lapping is useful for both gross and precise removal of material.

Applicants respectfully request reconsideration of the claims in light of the above amendment and the following remarks.

Claim Rejections – 35 U.S.C. § 102

Claims 1-4, 8, 9, 11, 13, and 21 are rejected under 35 USC § 102(b) as being anticipated by U.S. Patent No. 5,318,926 to Dlugokecki (“Dlugokecki”). Specifically, the Examiner stated that Dlugokecki discloses reshaping the encapsulant by a lapping process, citing Dlugokecki’s col. 7, lines 16-68 and Figures 4-8.

In light of the agreement reached on May 24, 2004, Claim 1 is patentable over Dlugokecki, which does not disclose lapping. Claims 2-4, 8, 9, 11, 13, and 21 depend from Claim 1 and are therefore patentable over Dlugokecki for the same reason as Claim 1.

Claim Rejections – 35 USC § 103

Claims 5-7, 10, 12, 14, 15-20, and 22 were rejected under 35 USC § 103 in view of various combinations of Dlugokecki and other references. However, none of the cited references disclose or suggest using lapping for encapsulant removal in a chip. Since Claims 5-7, 10, 12,

14, 15-20, and 22 depend from Claim 1, they are patentable over the cited combination of references at least for the same reason as Claim 1.

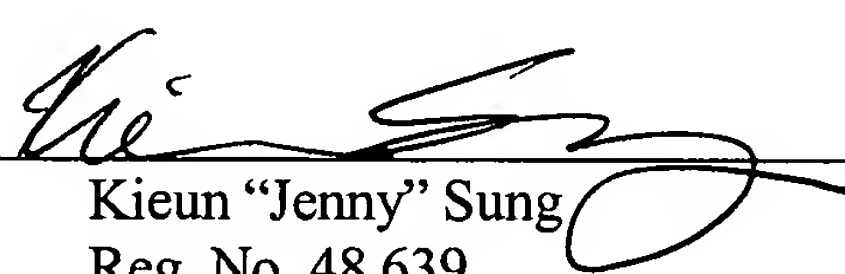
Conclusion

Applicants requests reconsideration of Claims 1-22 in light of the above amendments and remarks. If the Examiner wishes to discuss any aspect of this application, the Examiner is invited to telephone Applicants' undersigned attorney at 650-833-2121.

Any fee due for this Amendment may be charged to Deposit Account No. 07-1896.

Respectfully submitted,

Dated: June 4, 2004


Kieun "Jenny" Sung
Reg. No. 48,639
Attorney for Applicants

GRAY CARY WARE & FREIDENRICH LLP
2000 University Avenue
East Palo Alto, CA 94303-2248
(650) 833-2000

KJS